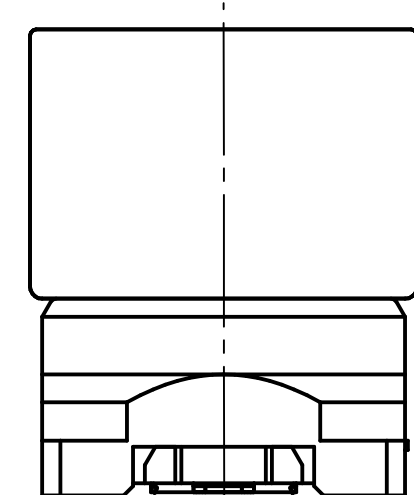
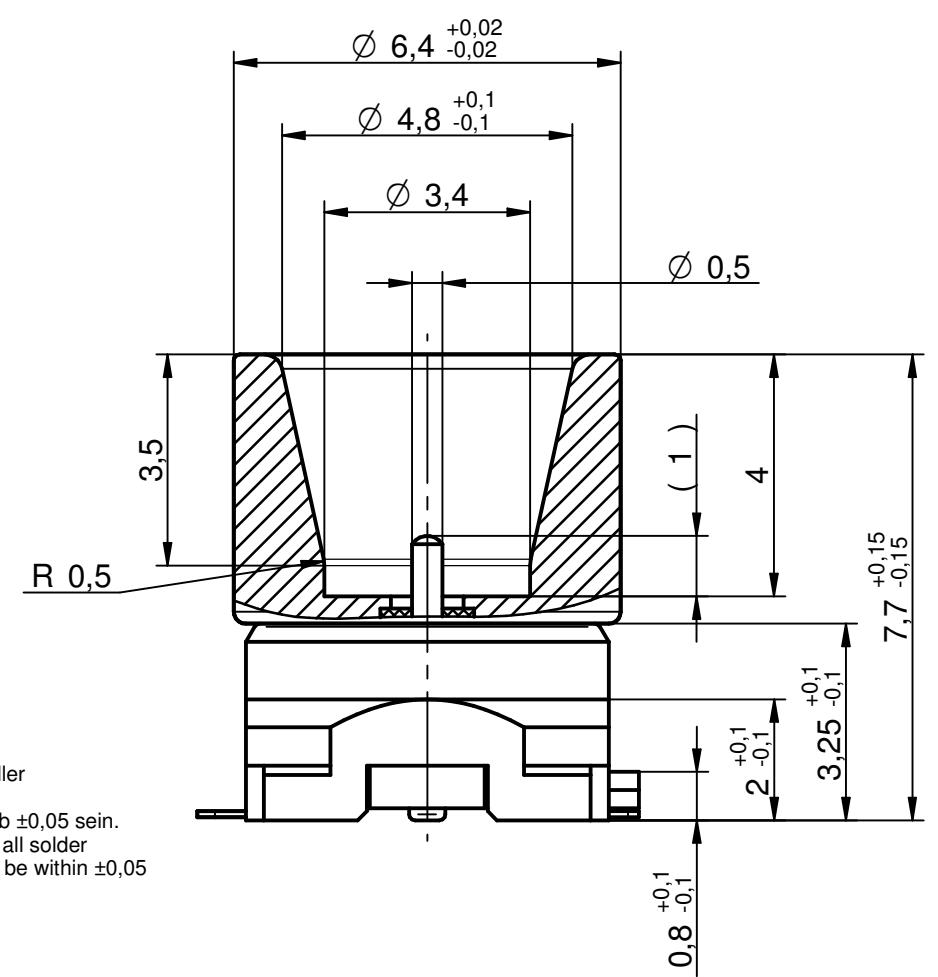


Orientation lug (2x)  
Orientierungsnasen (2x)

Koplanarität aller Lötflächen muss innerhalb  $\pm 0,05$  sein.  
Coplanarity of all solder surfaces must be within  $\pm 0,05$

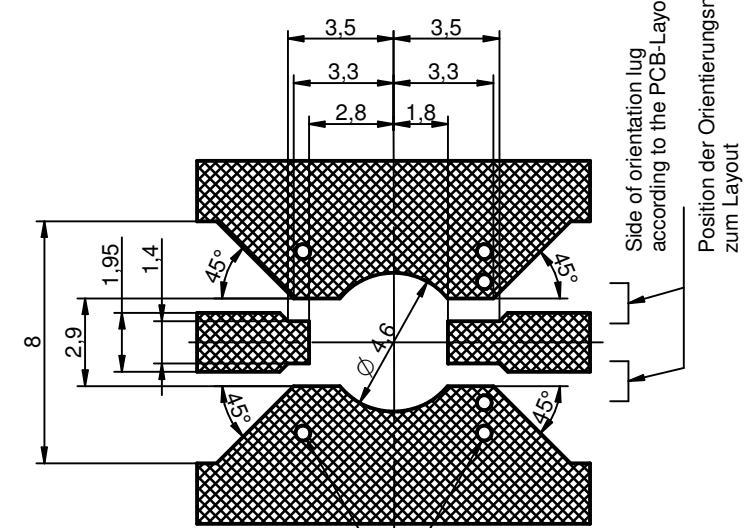


Anmerkung / Note:  
Maximal zulässige Temperaturbelastung: 250°C  
Maximally allowed temperature stress: 250°C

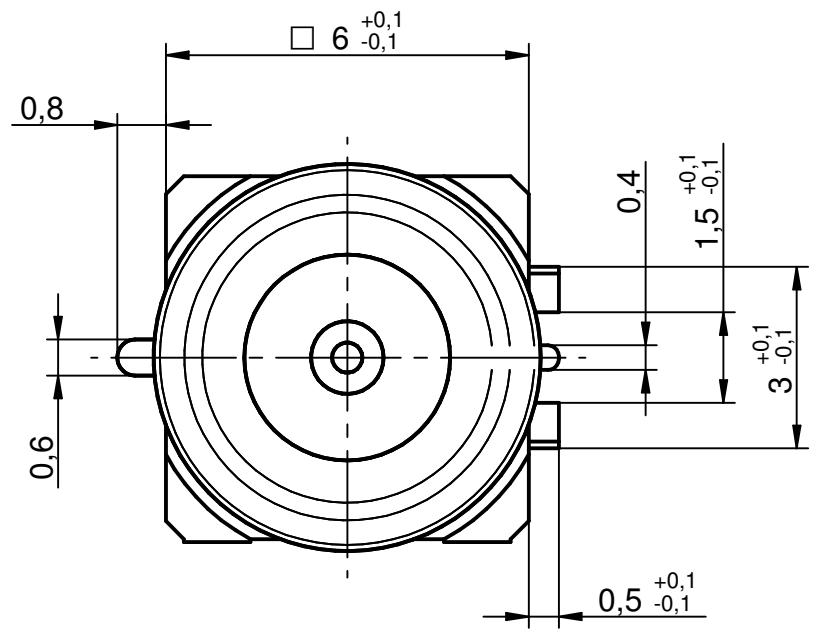
Verpackung / Packaging:  
Blistergurt AGK-3357 / 350Stück  
Tape and reel AGK-3357 / 350 pcs

Multilayer PCB under Switch have to be matched 50Ohm  
Multilayer-Layout unter Schalter muss auf 50 Ohm abgestimmt sein.

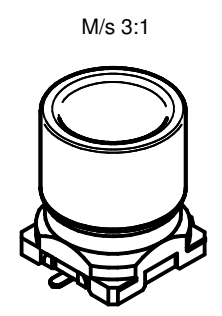
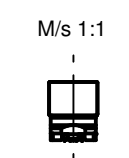
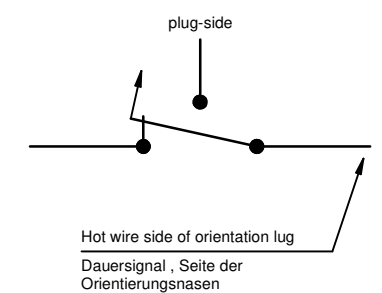
SMT-Solderpad layout proposal:  
SMT-Lötflächen:



Via holes  
Durchkontaktierungen

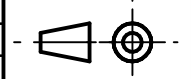


Switch function of front view:



	Material	Beschichtung / Plating
Gehäuse / Housing	Gd-ZnAl4Cu1	8-12µm Cu +2µm NiP + 0,15µm Au
Isolierung / Insulator	PA 46	
Federn / Springs	Kupfer Beryllium / Copper Beryllium	Ni + 0,2µm Au
Dichtscheibe / Gasket	Silikon Gummi / Silicon rubber	
Restteile / Other parts	Messing / Brass	2µm NiP + 0,15µm Au

IMS CONNECTOR SYSTEMS		general toleranc ISO 2768		scale: 8:1	
		mH angle: $\pm 5^\circ$		Assembly instruction: Stripping dimension:	
	date	name		SMT-Schalter SMT-Switch	
	generate 15.08.11	Pölz			
	checked				
	Norm			4930.99.0030.003	
EC_054_18	b	Revised	18.06.18		
design	a	New revision	29.09.11	Pölz	b
nr.	rev.	alteration	date	name	



4930.99.0030.003

Rev. b